

**HIGH-SIDE AND LOW-SIDE GATE DRIVERS IN SO-16**
**Description**

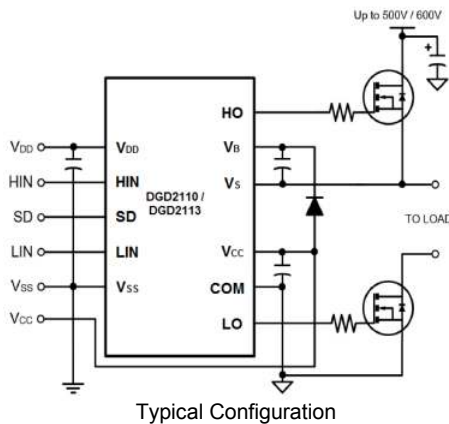
The DGD2110 and DGD2113 are high-voltage/high-speed MOSFET and IGBT drivers with independent high-side and low-side outputs. The high-side driver features floating supply for operation at up to 500V/600V. The 10ns (max)/20ns (max) propagation delay matching between the high- and the low side drivers allows high-frequency operation.

The DGD2110 and DGD2113 logic inputs are compatible with standard CMOS levels (as low as 3.3V) while driver outputs feature high-pulse current buffers designed for minimum driver cross conduction.

The DGD2110 and DGD2113 are offered in a SO-16 package. They operate over an extended -40°C to +125°C temperature range.

**Applications**

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers



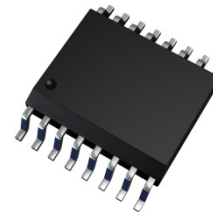
Typical Configuration

**Features**

- Drives two N-Channel MOSFETs or IGBTs in High-Side/Low-Side Configuration
- Floating High-Side Operates to 600V
- 2.5A Sink/2.5A Source Typical Output Currents
- Outputs Tolerant To Negative Transients
- Wide Gate Driver Supply Voltage Range: 10V to 20V
- Wide Logic Input Supply Voltage Range: 3.3V to 20V
- Wide Logic Supply Offset Voltage Range: -5V to 5V
- 15ns (typ) Rise/13ns (typ) Fall Times with 1000pF load
- 105ns (typ) Turn-On/94ns (typ) Turn-Off Delay Times
- Cycle-by-Cycle Edge-Triggered Shutdown Circuitry
- Extended Temperature Range: -40°C to +125°C
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact@diodes.com) or your local Diodes representative. <https://www.diodes.com/quality/product-definitions/>**

**Mechanical Data**

- Case: SO-16 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish—Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.130 grams (Approximate)


 SO-16  
Top View

**Ordering Information** (Note 4)

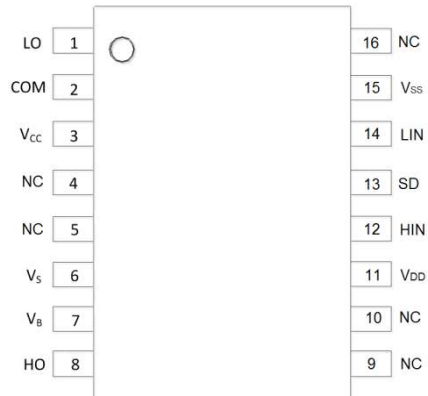
| Product       | Marking | Reel size (inches) | Tape width (mm) | Quantity per reel |
|---------------|---------|--------------------|-----------------|-------------------|
| DGD2110S16-13 | DGD2110 | 13                 | 16              | 1500              |
| DGD2113S16-13 | DGD2113 | 13                 | 16              | 1500              |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**


= Manufacturer's Marking  
 DGD211x = Product Type Marking Code (See Table Above)  
 YY = Year (ex: 19 = 2019)  
 WW = Week (01 - 53)

## Pin Diagrams

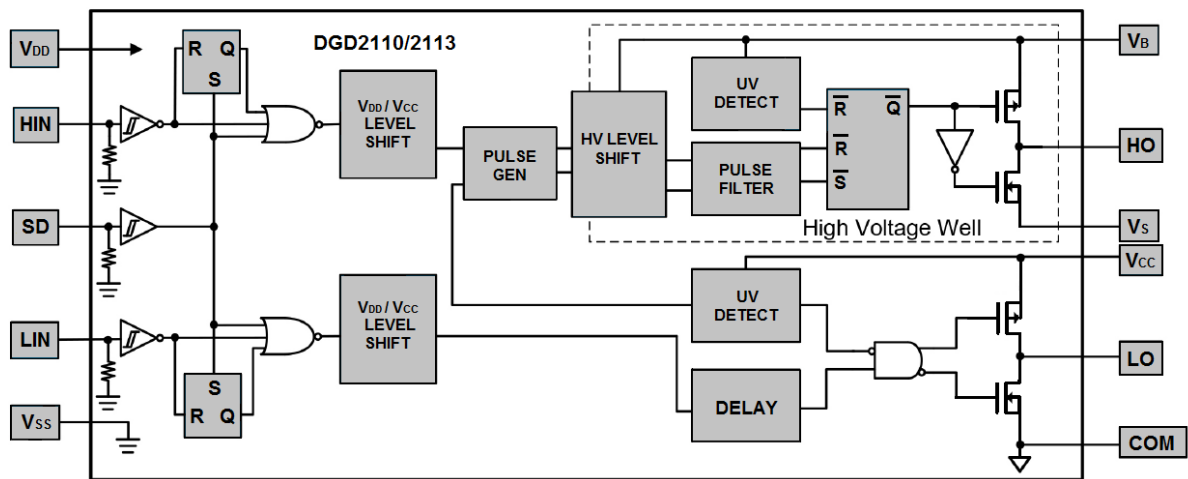


Top view: SO-16

## Pin Descriptions

| Pin Number  | Pin Name        | Function  |
|-------------|-----------------|---|
| 1           | LO              | Low-side gate driver output pin   |
| 2           | COM             | Low-side gate driver power supply return pin                              |
| 3           | V <sub>CC</sub> | Low-side gate driver power supply pin                                     |
| 4,5,9,10,16 | NC              | No connect pin (No Internal Connection)                                   |
| 6           | V <sub>S</sub>  | High-side gate driver floating power supply return pin                    |
| 7           | V <sub>B</sub>  | High-side gate driver floating power supply pin                           |
| 8           | HO              | High-side gate drive output pin   |
| 11          | V <sub>DD</sub> | Logic power supply pin  |
| 12          | HIN             | Logic input pin for high-side gate driver output. HIN and HO are in phase |
| 13          | SD              | Logic input shutdown pin  |
| 14          | LIN             | Logic input pin for low-side gate driver output. LIN and LO are in phase  |
| 15          | V <sub>SS</sub> | Logic ground pin  |

## Functional Block Diagram



**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                              | Symbol               | Value  | Unit |
|---|----------------------|--|------|
| High-Side Floating Supply Voltage (DGD2110) | V <sub>B</sub>       | -0.3 to +524                                 | V    |
| High-Side Floating Supply Voltage (DGD2113) | V <sub>B</sub>       | -0.3 to +624                                 | V    |
| High-Side Floating Supply Offset Voltage    | V <sub>S</sub>       | V <sub>B</sub> -24 to V <sub>B</sub> +0.3    | V    |
| High-Side Floating Output Voltage           | V <sub>HO</sub>      | V <sub>S</sub> -0.3 to V <sub>S</sub> +0.3   | V    |
| Offset Supply Voltage Transient             | dV <sub>S</sub> / dt | 50   | V/ns |
| Low-Side Fixed Supply Voltage               | V <sub>CC</sub>      | -0.3 to +24                                  | V    |
| Low-Side Output Voltage                     | V <sub>LO</sub>      | -0.3 to V <sub>CC</sub> +0.3                 | V    |
| Logic Supply Voltage                        | V <sub>DD</sub>      | -0.3 to V <sub>SS</sub> +24                  | V    |
| Logic Supply Offset Voltage                 | V <sub>SS</sub>      | V <sub>CC</sub> -24 to V <sub>CC</sub> +0.3  | V    |
| Logic Input Voltage (HIN, LIN, and SD)      | V <sub>IN</sub>      | V <sub>SS</sub> -0.3 to V <sub>DD</sub> +0.3 | V    |

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                                    | Symbol           | Value       | Unit |
|---|------------------|-------------|------|
| Power Dissipation Linear Derating Factor (Note 5) | P <sub>D</sub>   | 1.25        | W    |
| Thermal Resistance, Junction to Ambient (Note 5)  | R <sub>θJA</sub> | 90          | °C/W |
| Thermal Resistance, Junction to Case (Note 5)     | R <sub>θJC</sub> | 45          | °C/W |
| Operating Temperature                             | T <sub>J</sub>   | +150        | °C   |
| Lead Temperature (Soldering, 10 seconds)          | T <sub>L</sub>   | +300        |      |
| Storage Temperature Range                         | T <sub>STG</sub> | -55 to +150 |      |

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

**Recommended Operating Conditions**

| Parameter                                  | Symbol          | Min                 | Max                  | Unit |
|--|-----------------|---------------------|----------------------|------|
| High-Side Floating Supply Absolute Voltage | V <sub>B</sub>  | V <sub>S</sub> + 10 | V <sub>S</sub> + 20  | V    |
| High-Side Floating Supply Offset Voltage   | V <sub>S</sub>  | (Note 6)            | 500                  | V    |
| High-Side Floating Supply Offset Voltage   | V <sub>S</sub>  | (Note 6)            | 600                  | V    |
| High-Side Floating Output Voltage          | V <sub>HO</sub> | V <sub>S</sub>      | V <sub>B</sub>       | V    |
| Low-Side Fixed Supply Voltage              | V <sub>CC</sub> | 10                  | 20                   | V    |
| Low-Side Output Voltage                    | V <sub>LO</sub> | 0                   | V <sub>CC</sub>      | V    |
| Logic Supply Voltage                       | V <sub>DD</sub> | V <sub>SS</sub> + 3 | V <sub>SS</sub> + 20 | V    |
| Logic Supply Offset Voltage                | V <sub>SS</sub> | -5 (Note 7)         | 5                    | V    |
| Logic Input Voltage (HIN, LIN, and SD)     | V <sub>IN</sub> | V <sub>SS</sub>     | V <sub>DD</sub>      | V    |
| Ambient Temperature                        | T <sub>A</sub>  | -40                 | +125                 | °C   |

Notes: 6. Logic operation for V<sub>S</sub> = -4V to +500V.

7. When V<sub>DD</sub> < 5V, the minimum V<sub>SS</sub> offset is limited to -V<sub>DD</sub>.

**DC Electrical Characteristics** ( $V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ,  $V_{DD}$ ) = 15V,  $V_{SS}$  = COM, @ $T_A$  = +25°C unless otherwise specified.) (Note 8)

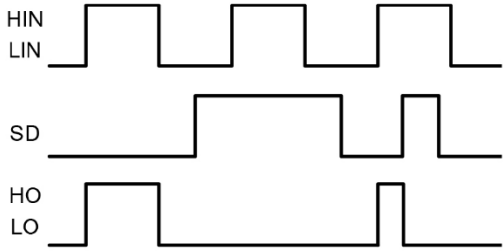
| Parameter   | Symbol      | Min | Typ | Max  | Unit    | Conditions  |
|---|-------------|-----|-----|------|---------|---|
| Logic "1" Input Voltage (Note 9)                      | $V_{IH}$    | 9.5 | —   | —    | V       | —   |
| Logic "0" Input Voltage (Note 9)                      | $V_{IL}$    | —   | —   | 6.0  | V       | —   |
| High Level Output Voltage, $V_{BIAS} - V_O$           | $V_{OH}$    | —   | —   | 1.4  | V       | $I_O = 0mA$   |
| Low Level Output Voltage, $V_O$                       | $V_{OL}$    | —   | —   | 0.15 | V       | $I_O = 20mA$  |
| Offset Supply Leakage Current                         | $I_{LK}$    | —   | —   | 50   | $\mu A$ | $V_B = V_S = 500V/600V$                               |
| Quiescent $V_{BS}$ Supply Current                     | $I_{BSQ}$   | —   | 55  | 230  | $\mu A$ | $V_{IN} = 0V$ or $V_{DD}$                             |
| Quiescent $V_{CC}$ Supply Current                     | $I_{CCQ}$   | —   | 56  | 340  | $\mu A$ | $V_{IN} = 0V$ or $V_{DD}$                             |
| Quiescent $V_{DD}$ Supply Current                     | $I_{DDQ}$   | —   | 0.6 | 30   | $\mu A$ | $V_{IN} = 0V$ or $V_{DD}$                             |
| Logic "1" Input Bias Current                          | $I_{IN+}$   | —   | 20  | 40   | $\mu A$ | $V_{IN} = V_{DD}$                                     |
| Logic "0" Input Bias Current                          | $I_{IN-}$   | —   | —   | 5.0  | $\mu A$ | $V_{IN} = 0V$   |
| $V_{BS}$ Supply Undervoltage Positive Going Threshold | $V_{BSUV+}$ | 7.5 | 8.6 | 9.7  | V       | —   |
| $V_{BS}$ Supply Undervoltage Negative Going Threshold | $V_{BSUV-}$ | 7.0 | 8.2 | 9.4  | V       | —   |
| $V_{CC}$ Supply Undervoltage Positive Going Threshold | $V_{CCUV+}$ | 7.4 | 8.5 | 9.6  | V       | —   |
| $V_{CC}$ Supply Undervoltage Negative Going Threshold | $V_{CCUV-}$ | 7.0 | 8.2 | 9.4  | V       | —   |
| Output High Short Circuit Pulsed Current              | $I_{O+}$    | 2.0 | 2.5 | —    | A       | $V_O = 0V$ , $V_{IN} = V_{DD}$ ,<br>$PW \leq 10\mu s$ |
| Output Low Short Circuit Pulsed Current               | $I_{O-}$    | 2.0 | 2.5 | —    | A       | $V_O = 15V$ , $V_{IN} = 0V$ ,<br>$PW \leq 10\mu s$    |

- Note:
- The  $V_{IN}$  and  $I_{IN}$  parameters are referenced to  $V_{SS}$  and are applicable to all three logic input pins: HIN, LIN, and SD. The  $V_O$  and  $I_O$  parameters are referenced to COM and are applicable to the respective output pins: HO and LO.
  - For optimal operation, it is recommended that the input pulses (HIN and LIN) should have a minimum amplitude of 9.5V ( $V_{DD} = 15V$ ) with a minimum pulse width of 200ns.

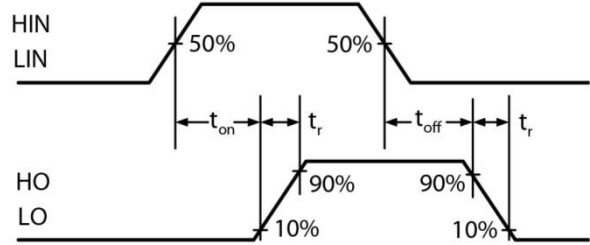
**AC Electrical Characteristics** ( $V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ,  $V_{DD}$ ) = 15V,  $C_L = 1000pF$ ,  $V_{SS} = COM$ , @ $T_A = +25^\circ C$ , unless otherwise specified.)

| Parameter                   | Symbol    | Min      | Typ | Max | Unit | Conditions        |
|-----------------------------|-----------|----------|-----|-----|------|-------------------|
| Turn-On Propagation Delay   | $t_{ON}$  | —        | 105 | 150 | ns   | $V_S = 0V$        |
| Turn-Off Propagation Delay  | $t_{OFF}$ | —        | 94  | 125 | ns   | $V_S = 500V/600V$ |
| Shut Down Propagation Delay | $t_{SD}$  | —        | 70  | 140 | ns   | $V_S = 500V/600V$ |
| Turn-On Rise Time           | $t_r$     | —        | 15  | 35  | ns   | —                 |
| Turn-Off Fall Time          | $t_f$     | —        | 13  | 25  | ns   | —                 |
| Delay Matching              | DGD2110   | $t_{DM}$ | —   | 10  | —    | —                 |
| Delay Matching              | DGD2113   | $t_{DM}$ | —   | 20  | —    | —                 |

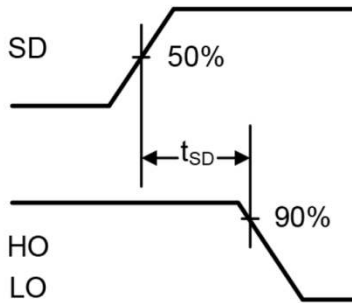
**Timing Waveforms**



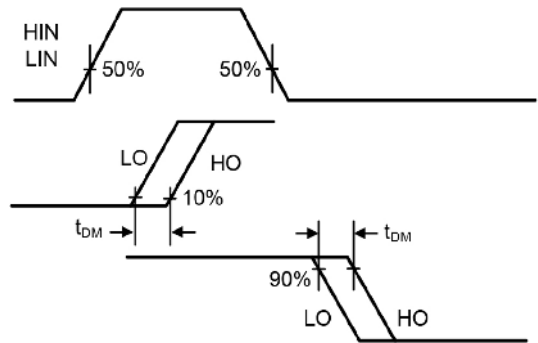
**Figure 1.** Input / Output Timing Diagram



**Figure 2.** Switching Time Waveform Definitions

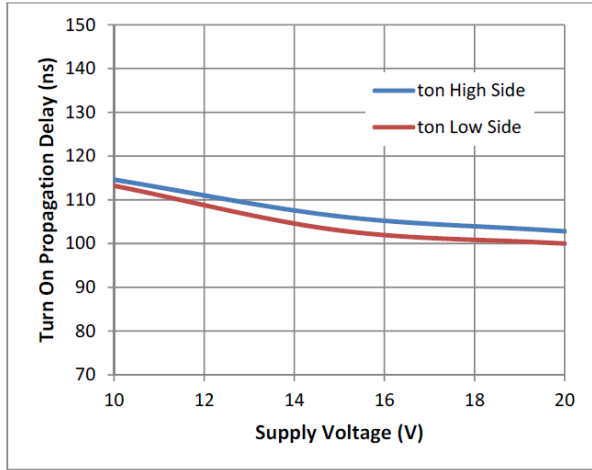


**Figure 3.** Shutdown Waveform Definitions

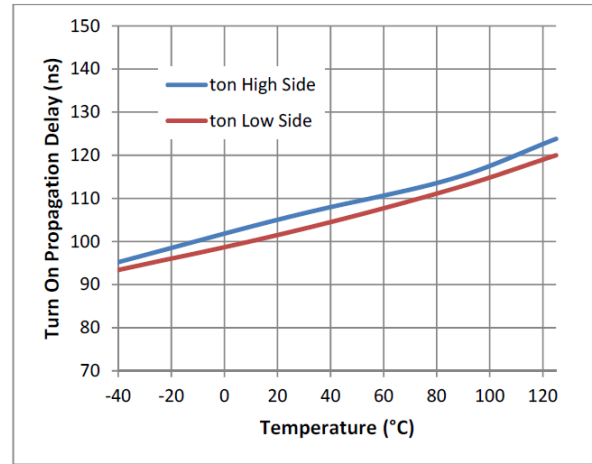


**Figure 4.** Delay Matching Waveform Definitions

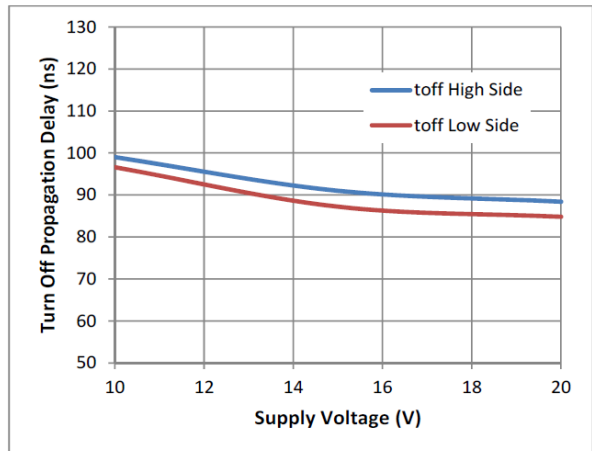
**Typical Performance Characteristics** ( $V_{CC}=15V$ ,  $@T_A = +25^\circ C$ , unless otherwise specified.)



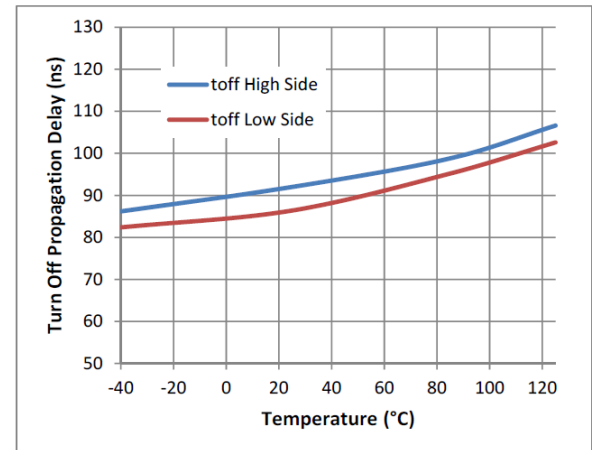
**Figure 5.** Turn-on Propagation Delay vs. Supply Voltage



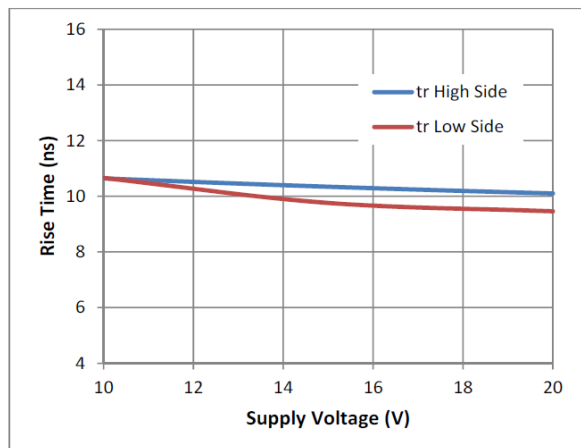
**Figure 6.** Turn-on Propagation Delay vs. Temperature



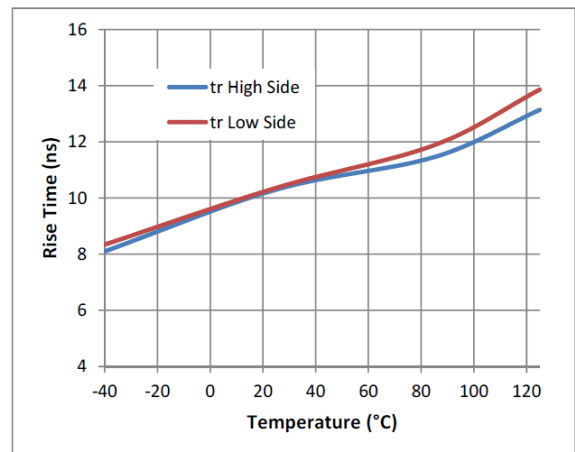
**Figure 7.** Turn-off Propagation Delay vs. Supply Voltage



**Figure 8.** Turn-off Propagation Delay vs. Temperature

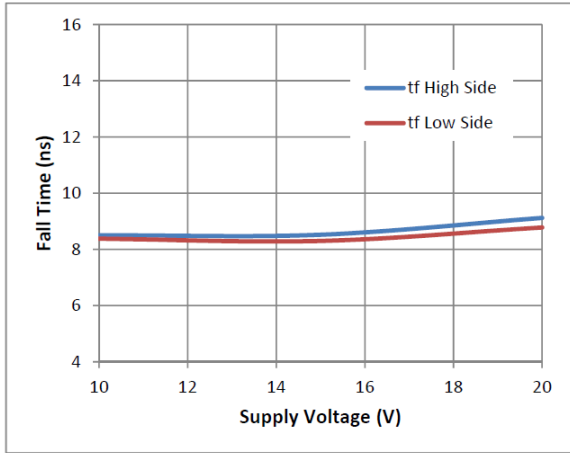


**Figure 9.** Rise Time vs. Supply Voltage

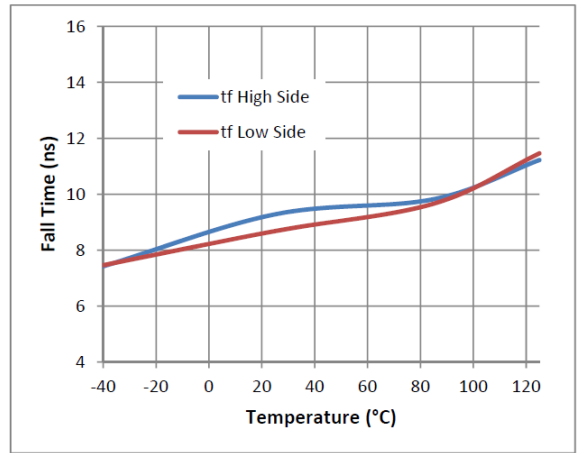


**Figure 10.** Rise Time vs. Temperature

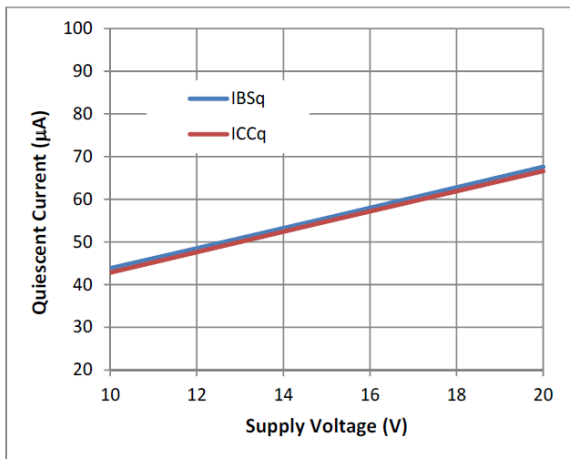
**Typical Performance Characteristics** (continued)



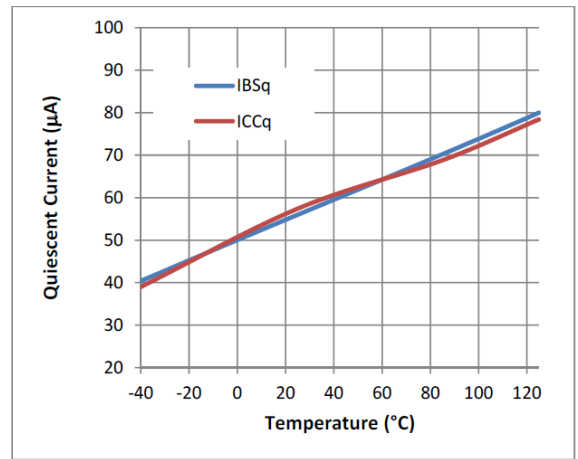
**Figure 11.** Fall Time vs. Supply Voltage



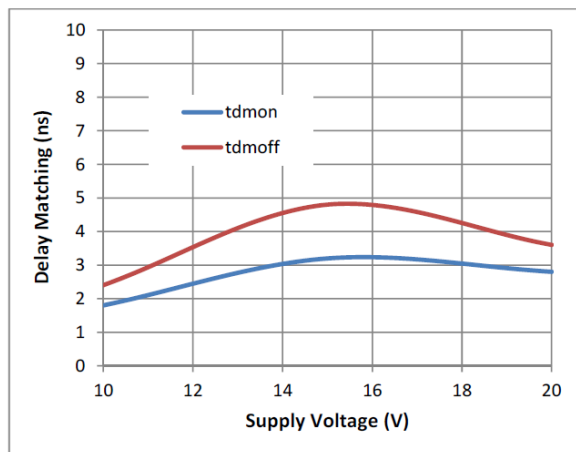
**Figure 12.** Fall Time vs. Temperature



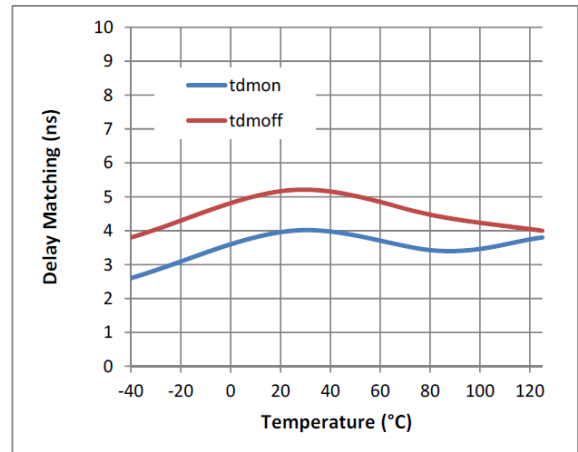
**Figure 13.** Quiescent Current vs. Supply Voltage



**Figure 14.** Quiescent Current vs. Temperature

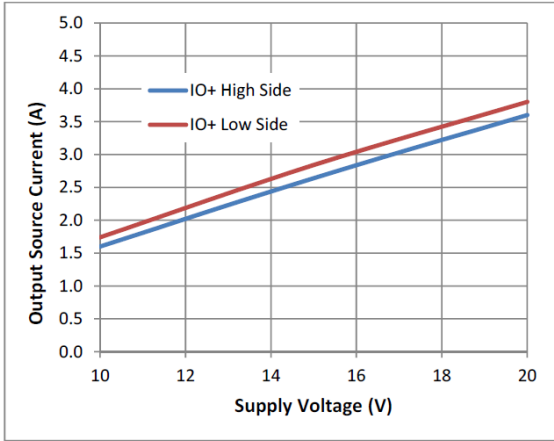


**Figure 15.** Delay Matching vs. Supply Voltage

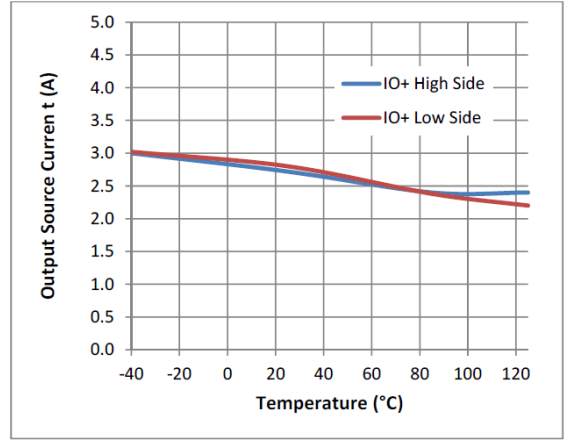


**Figure 16.** Delay Matching vs. Temperature

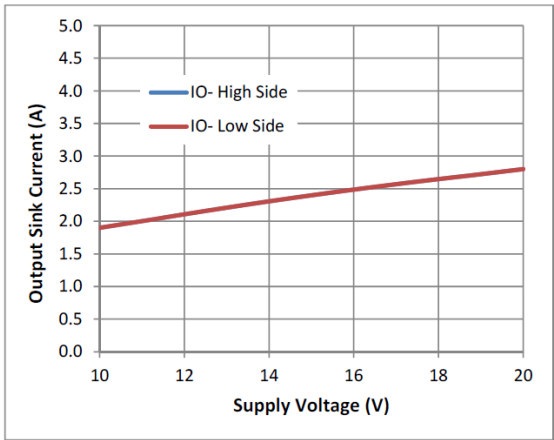
**Typical Performance Characteristics (cont.)**



**Figure 17.** Output Source Current vs. Supply Voltage

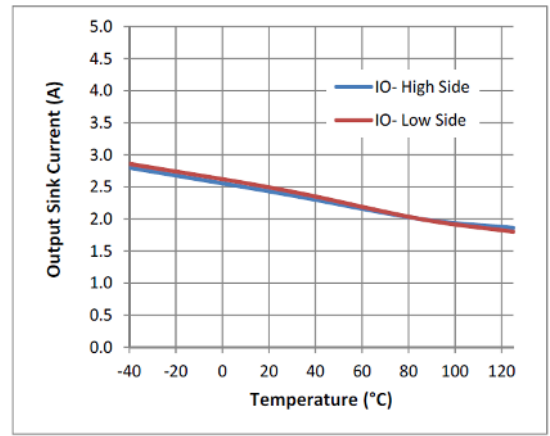


**Figure 18.** Output Source Current vs. Temperature

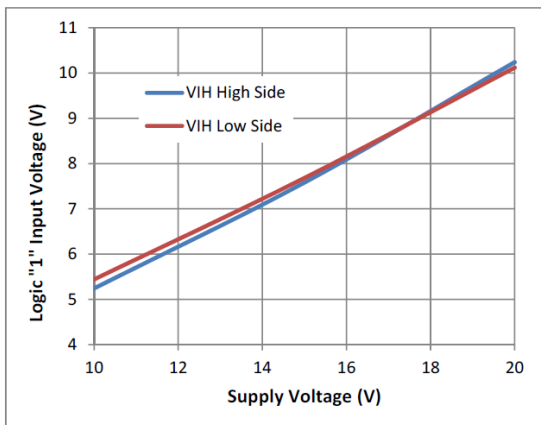


**Figure 19.** Output Sink Current vs. Supply Voltage

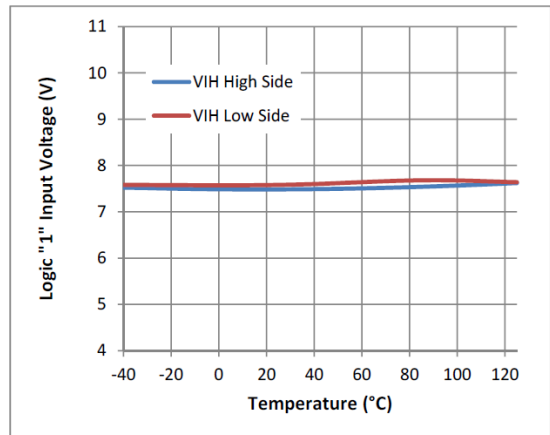
Note: graphs overlap one another



**Figure 20.** Output Sink Current vs. Temperature



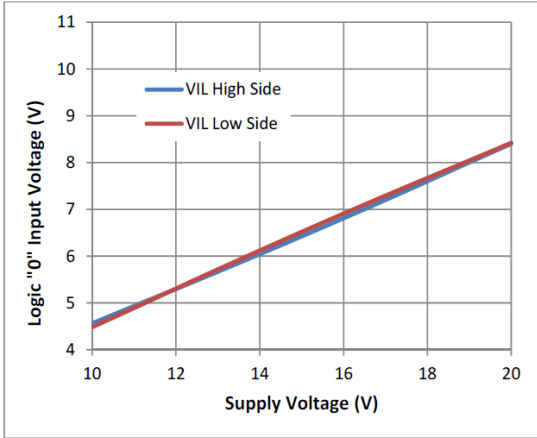
**Figure 21.** Logic 1 Input Voltage vs. Supply Voltage



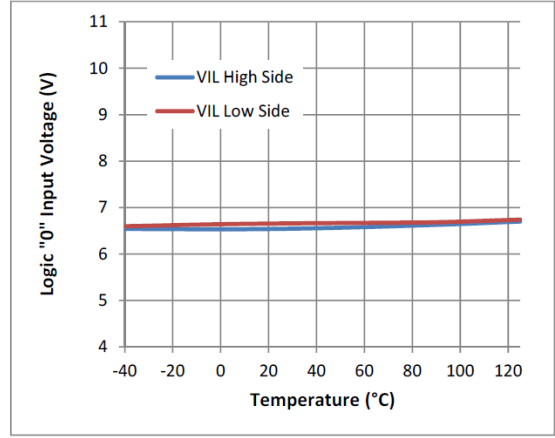
**Figure 22.** Logic 1 Input Voltage vs. Temperature



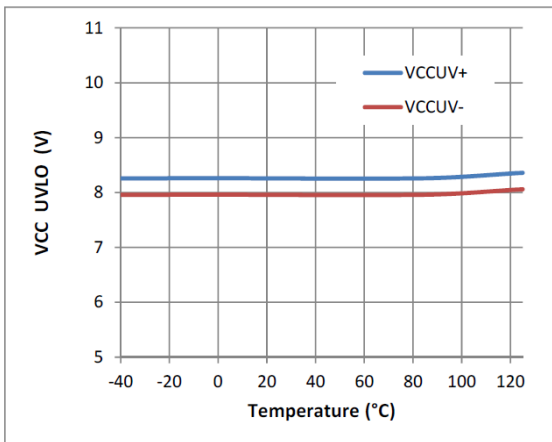
**Typical Performance Characteristics** (cont.)



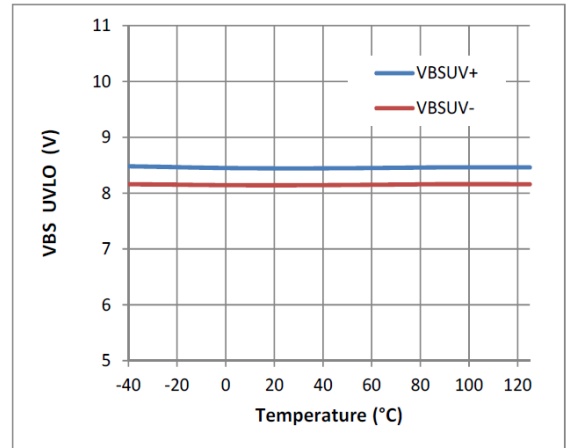
**Figure 23.** Logic 0 Input Voltage vs. Supply Voltage



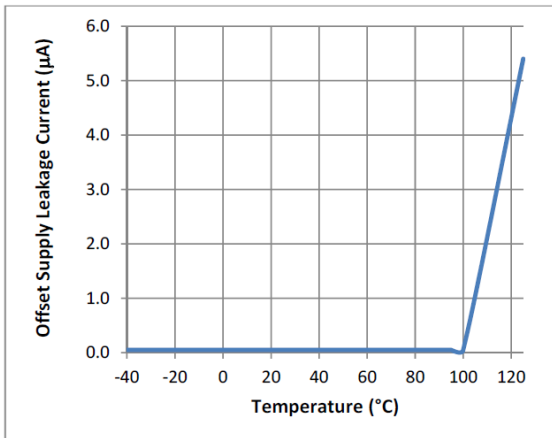
**Figure 24.** Logic 0 Input Voltage vs. Temperature



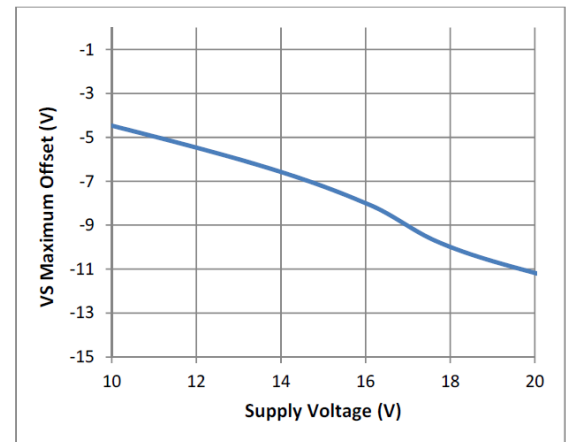
**Figure 25.** V<sub>CC</sub> UVLO vs. Temperature



**Figure 26.** V<sub>BS</sub> UVLO vs. Temperature

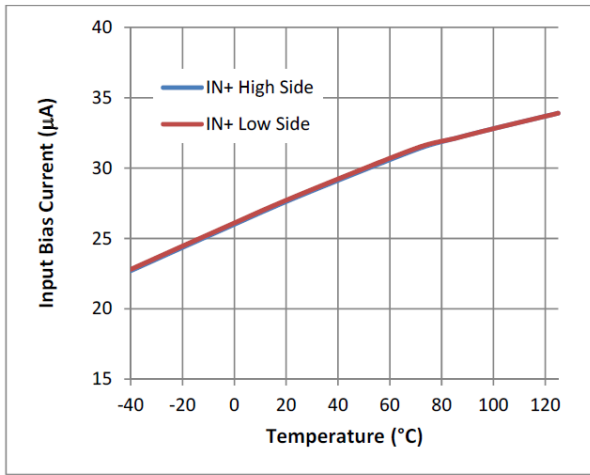


**Figure 27.** Offset Supply Leakage Current vs. Temperature

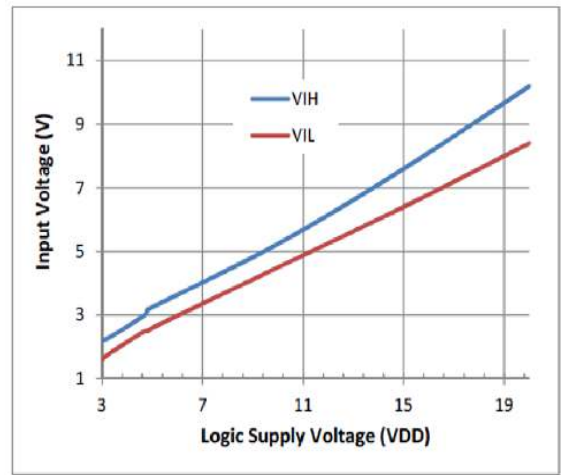


**Figure 28.** V<sub>S</sub> Maximum Offset vs. Supply Voltage

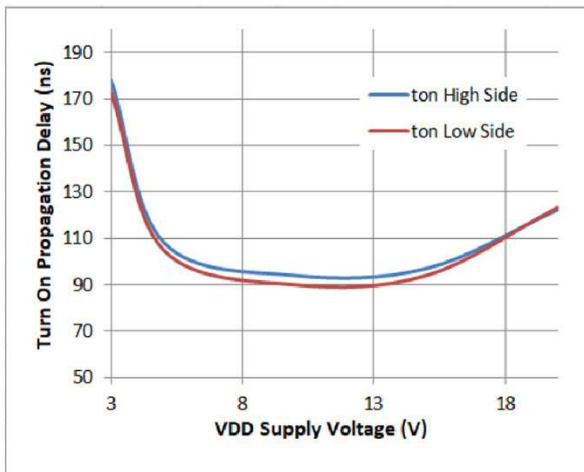
**Typical Performance Characteristics** (cont.)



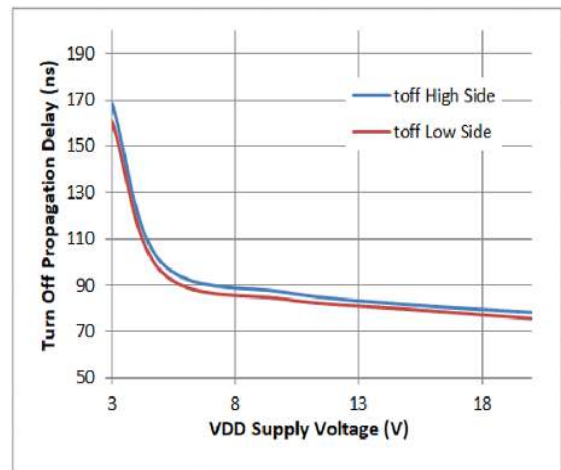
**Figure 29.** Input Bias Current vs. Temperature



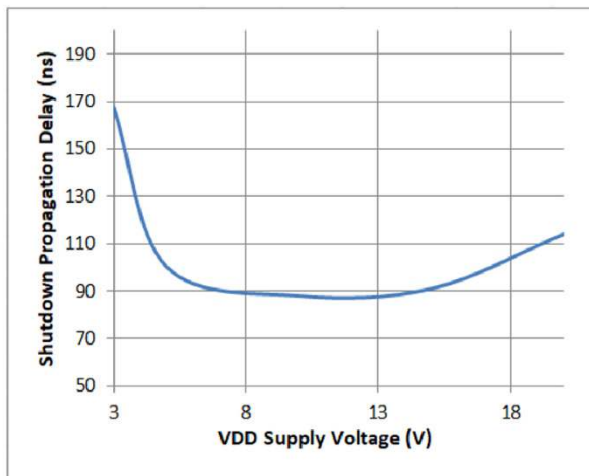
**Figure 30.** Input Voltage vs. Logic Supply Voltage



**Figure 31.** Turn-On Propagation Delay vs. Logic Supply Voltage



**Figure 32.** Turn-Off Propagation Delay vs. Logic Supply Voltage

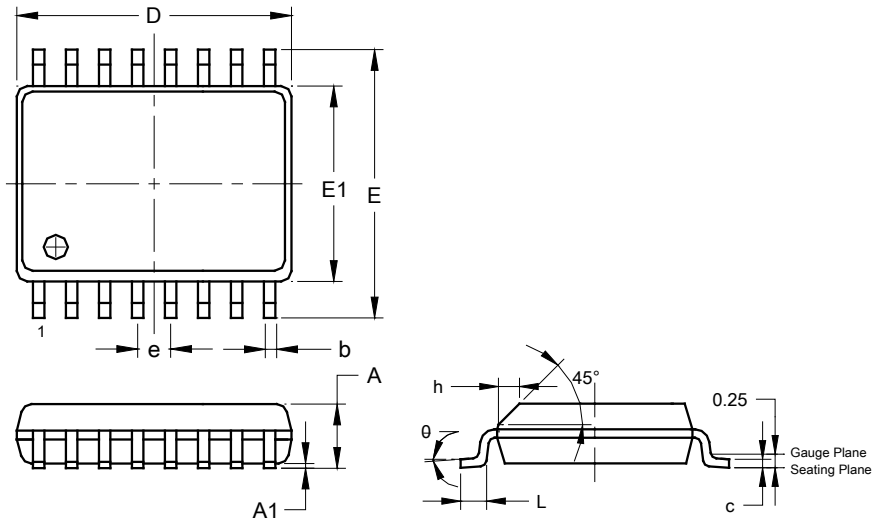


**Figure 33.** Shutdown Propagation Delay vs. Logic Supply Voltage

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SO-16 (Type TH)**

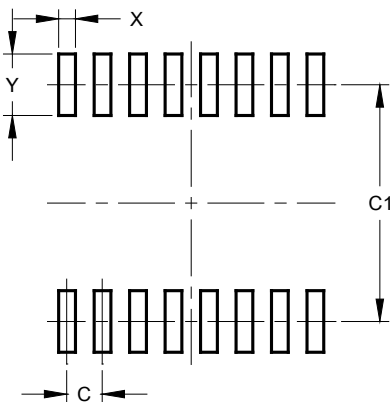


| SO-16 (Type TH)             |       |       |       |
|-----------------------------|-------|-------|-------|
| Dim                         | Min   | Max   | Typ   |
| A                           | 2.36  | 2.64  | --    |
| A1                          | 0.10  | 0.30  | --    |
| b                           | 0.33  | 0.51  | --    |
| c                           | 0.229 | 0.318 | --    |
| D                           | 10.11 | 10.46 | 10.29 |
| E                           | 10.01 | 10.64 | 10.33 |
| E1                          | 7.42  | 7.59  | 7.52  |
| e                           | --    | --    | 1.27  |
| h                           | --    | --    | 0.48  |
| L                           | 0.41  | 1.27  | --    |
| theta                       | 0°    | 8°    | --    |
| <b>All Dimensions in mm</b> |       |       |       |

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SO-16 (Type TH)**



| Dimensions | Value (in mm) |
|------------|---------------|
| C          | 1.27          |
| C1         | 8.46          |
| X          | 0.60          |
| Y          | 2.20          |

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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